



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<b>TO:</b>	Please return this copy as a certification of your approval
<b>Part No.:</b>	<b>Checked &amp; Approved by:</b>
<b>Customer's Part No.:</b>	<b>Date:</b>

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Part No.	:	SF1622
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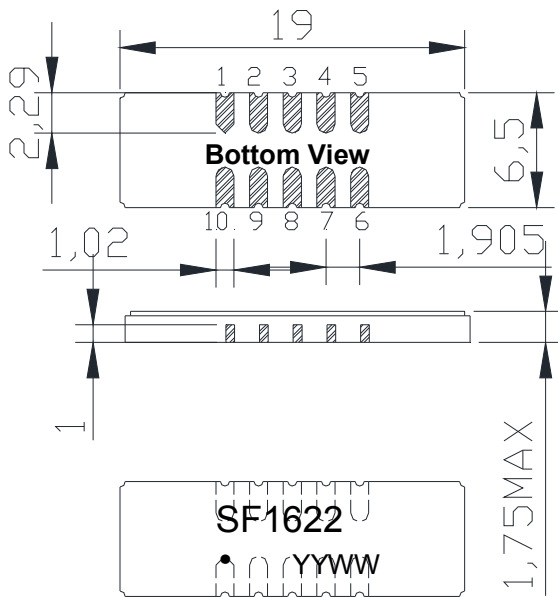
**Application**

- Low -loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable Passband 0.06 MHz

**Features**

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 19.00x6.50x1.75mm<sup>3</sup>
- Package Code SMD19
- **Electrostatic Sensitive Device(ESD)**

**Package Dimensions (Unit: mm)**



**Pin Configuration**

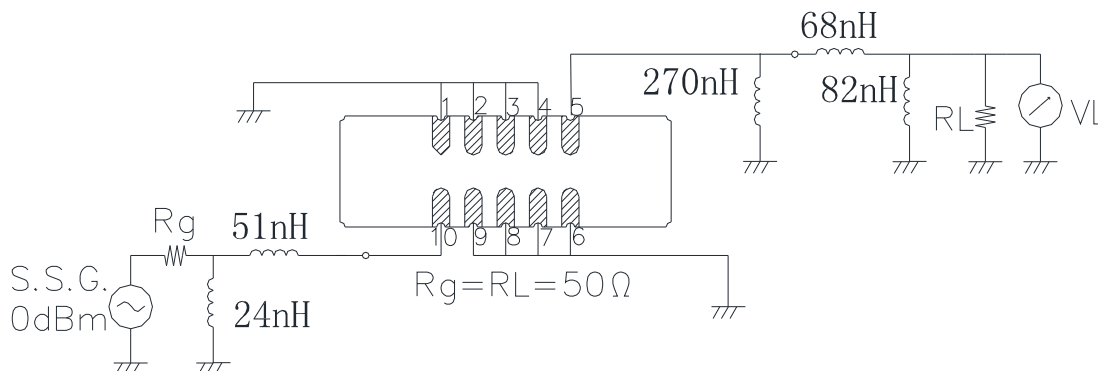
Pin No.	Description
10	Input
5	Output
1,2,3,4,6,7,8,9	Ground

**Marking Description**

<b>S</b>	Trademark
<b>F</b>	SAW Filter
<b>1622</b>	Part Number
●	Pin 1
<b>YYWW</b>	Year Code & Week Code

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

**Test Circuit(Bottom View)**



**Performance****Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	T	-10 ~ +65	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

**Electronic Characteristics**

Test Temperature: 25°C ± 2°C

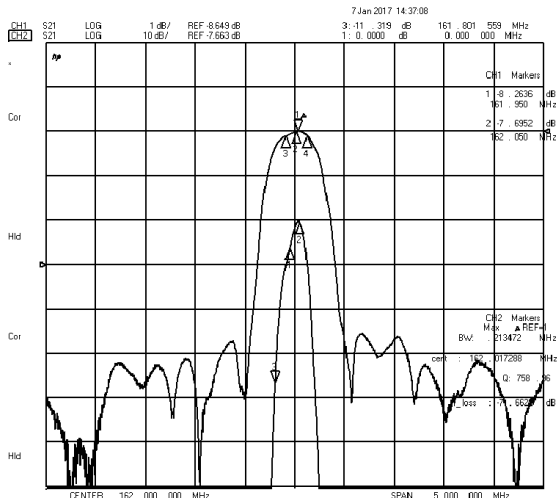
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

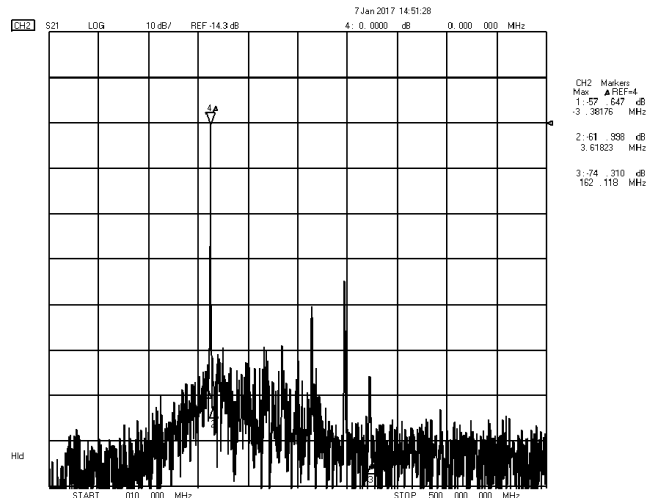
Item		Minimum	Typical	Maximum	Unit
Center Frequency	f <sub>c</sub>		162.00		MHz
Insertion Loss(min) 161.95-162.05MHz	IL		8.0	10.0	dB
1 dB Usable Bandwidth	BW <sub>1dB</sub>	0.06			MHz
1 dB Bandwidth	BW <sub>1dB</sub>	0.06	0.2		MHz
Group Delay Ripple 161.95-162.05MHz	GDR		0.4	1.0	us
Phase Consistency 161.97-162.03MHz (Every 4 pieces)				10	deg
Absolute Attenuation	α				
158.50MHz		50.0	52.0		dB
161.50MHz		40.0	42.0		dB
162.50MHz		40.0	42.0		dB
165.50MHz		50.0	52.0		dB
324.00MHz		50.0	55.0		dB
Input VSWR 161.95-162.05MHz			2.3:1	2.5:1	/
Output VSWR 161.95-162.05MHz			2.3:1	2.5:1	/

Frequency Characteristics

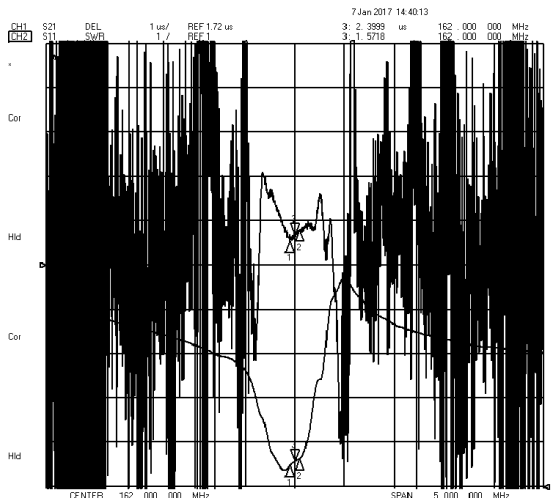
Frequency Response



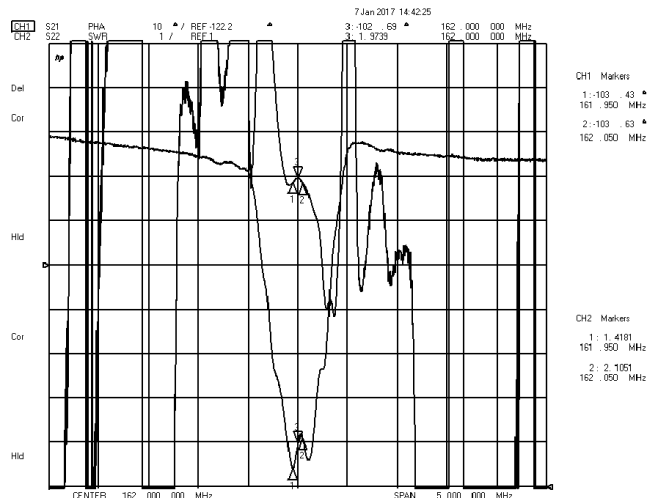
Frequency Response (wideband)



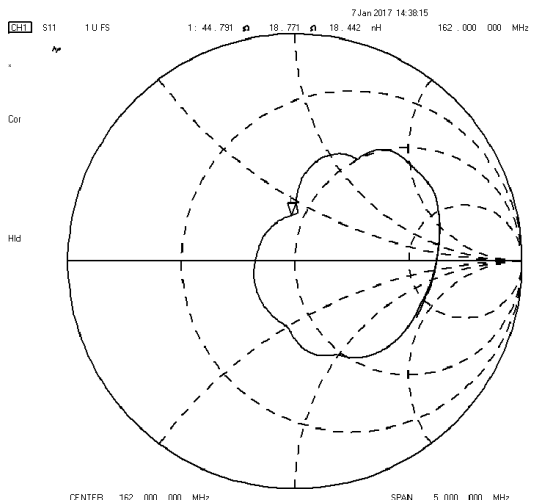
Delay Ripple & S11 VSWR



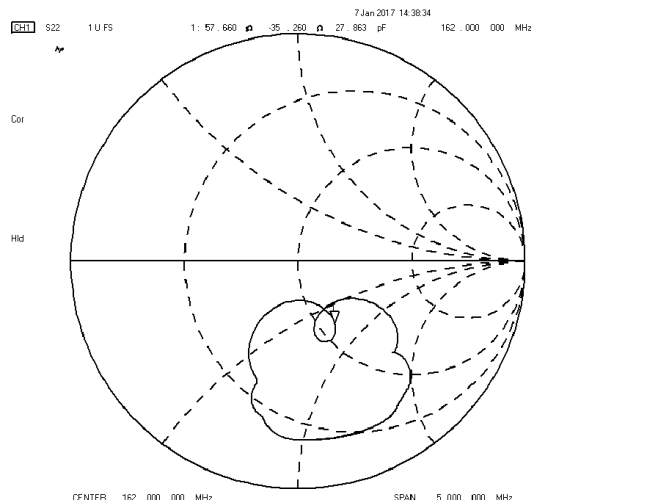
Phase Linearity & S22 VSWR



S11 Smith Chart



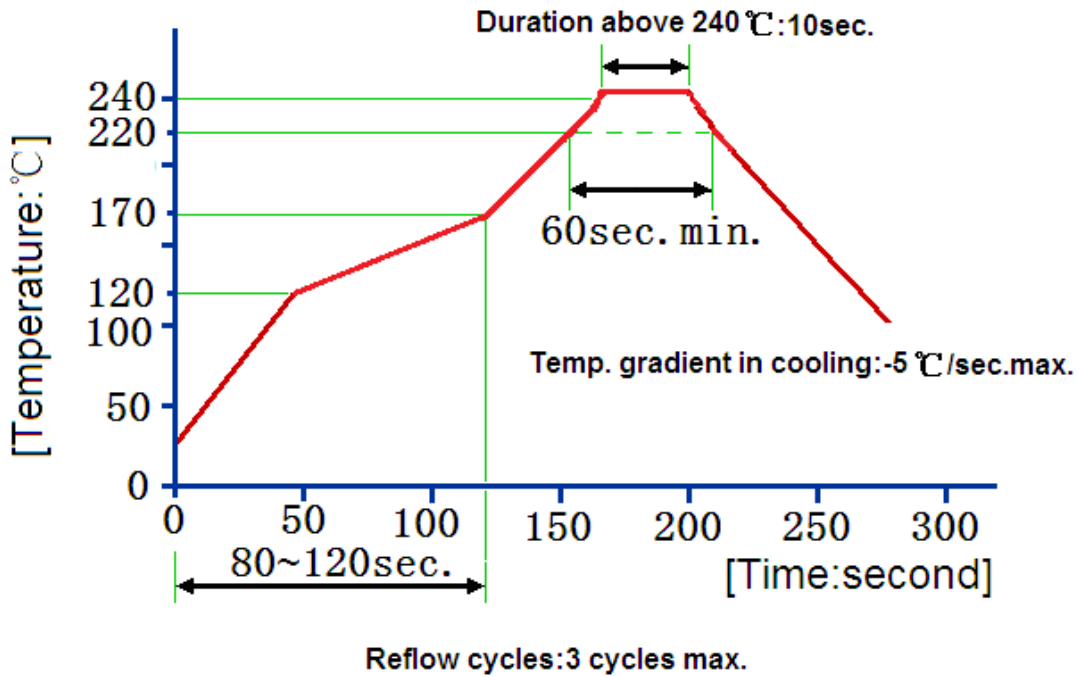
S22 Smith Chart



**Reliability (The SAW components shall remain electrical performance after tests)**

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: -55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60°C±2°C , 90~95% RH                          Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz                          Amplitude:1.5mm Directions: X,Y and Z                          Duration: 2h
5	Drop Test	Cycle time: 10 times                          Height: 1.0m
6	Solder Ability Test	Temperature: 245°C±5°C                          Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2)Temperature of Soldering Iron: 350°C±10°C , Duration: 3~4s , Recovery time : 2 ± 0.5h

**Recommended Reflow Soldering Diagram**



**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.